In the Specification

Page 4, lines 17-18 replace the paragraph as follows:

Fig. 18 is a view of a substrate fragment processed ~~in~~ in accordance with the invention.

The paragraph beginning at line 22 on page 13 has been amended as shown below:

The illustrated projecting apexes actually project in to half-way into the thickness of the bonding pads, a distance of approximately ~~on-half~~ one-half "A". The penetration stop surface 62 described with reference to Fig. 5 provides a stopping point for preventing the projecting points from extending further into bonding pads 88 than would be desired. In connecting the testing apparatus to chip 85, pressure would be monitored during engagement of the projecting tips relative to the pads 88. At some point during the projection, the force or back pressure against the testing apparatus would geometrically increase as the penetration stop plane reaches the outer surface of the bonding pads 88, indicating that full penetration had occurred. At this point, the testing substrate and chip 85 would be effectively electrically engaged. An electric signal would be sent between the respective grouping of apexes and respective test pads in conventional testing methods to evaluate operability of integrated circuitry formed within the semiconductor substrate 85.